

# **Oxidation Behavior and In-Cell Performance of Developmental SOFC Interconnect Alloys**

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Materials Issues for Distributed Energy Resources  
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# Exploratory Effort

- Background- Key issues for metallic interconnects
- First Screening: Microalloyed Ni and ferritic alloy
  - Oxidation
  - Electrical Resistivity
  - In-Cell Performance
- Results on oxidation (volatility) and electrical resistivity studies for 2nd series of ferritic alloys
- Concluding remarks

# Metallic Interconnects in SOFC Fuel Cells

Key Interconnect Functions are to Electrically Connect Series of Cells into Stacks and to Separate Fuel/Oxidant

- Environment: 700-850°C, Oxidizing/Reducing, Thermal expansion compatibility with ceramic cell components is important in some designs
- Benchmark: Coated Cr-5Fe-1Y<sub>2</sub>O<sub>3</sub> or Doped Perovskite Ceramic (\$, Brittle)

# Advantages of Planar Metallic Interconnects

- Potentially Significantly Lower Cost Than Ceramics
  - Raw Materials and Processing/Machining
- Mechanical Integrity-Thinner Plates than Ceramics
- Dense (Important for Fuel/Oxidant Separation)
- Potential for Better Performance Due to High Electrical Conductivity

# **Major Issue for Metallic Interconnects is Maintenance of Electrical Conductivity**

- Metals Oxidize in Fuel Cell Environments
- Oxidation Products Usually Electrically Resistive, Can Contaminate/Degrade Other Cell Components
- Manage Surface Chemistry via Alloy Design and Processing to Maintain Sufficient Electrical Conductivity

# No Clear Choice for Metallic Interconnects

Oxide	Max Theoretical Scaling Limit	*Bulk Resistivity (ohm-cm)	*Source
SiO <sub>2</sub>	1750°C	7 X 10 <sup>6</sup> 600°C	44 <sup>th</sup> CRC
Al <sub>2</sub> O <sub>3</sub>	1450°C	5 X 10 <sup>8</sup> 700°C	MSE CRC
Cr <sub>2</sub> O <sub>3</sub>	1100°C	1 X 10 <sup>2</sup> 800°C	Holt+Kofstad
NiO	850°C	5-7 X 10 <sup>0</sup> 900°C	Nowotny + Sorrell
CoO	700°C	1 X 10 <sup>0</sup> 950°C	Nowotny +

- SiO<sub>2</sub>, Al<sub>2</sub>O<sub>3</sub> too insulating
- Cr<sub>2</sub>O<sub>3</sub>: high volatility-contaminates cell, borderline resistivity
- NiO,CoO: high CTE, sulfur, borderline scaling

## Options are Limited

- No Uncoated, Non-Precious Metal Viable Above 850°C
- Ni/NiO has a Chance in Range of 700 to 850°C if Successfully Doped to Lower Scale Growth Rate
  - No volatility issues
  - Noble (won't oxidize) in fuel-side environment
  - Fuel Sulfur Impurities May Lead to Low Melting Ni-S Compounds
  - CTE mismatch requires use as coating (substrate interdiffusion)
- Literature Data Suggests Conventional Cr<sub>2</sub>O<sub>3</sub>-Formers Not Viable Above ~700-800°C (possibly lower). Will need to:
  - Microalloy to reduce scale growth rate/increase scale conductivity
  - Reduce volatility

# No One Alloy May be Able to Meet Conductivity and CTE Requirements

- Optimize for Scale Growth Rate and Conductivity
  - May require different alloy for anode/cathode environments
  - May not be possible to co-optimize for CTE compatibility
- Eventual Implementation as Cladding or Coating on CTE Optimized Alloy Substrate
- Investigate **Microalloyed Ni** and **Microalloyed Ferritic**

# Candidate Alloys

- Microalloyed Ni

- Hot-Pressed Ni-0.3Y<sub>2</sub>O<sub>3</sub> Wt.%, Cast/Rolled Ni-0.15Y Wt.%
- Hot-Pressed Li-Doped Ni-0.3Y<sub>2</sub>O<sub>3</sub> (0.07 wt.%, 0.6 at.% Li)
- Rationale:
  - Y or Y<sub>2</sub>O<sub>3</sub> to reduce NiO growth rate
  - Li to reduce NiO growth rate, increase conductivity

- Microalloyed Ferritic (Based on Quadakkers et al.)

- Cast and Rolled Fe-25Cr-1Mn-0.5Ti-0.4La wt.%
- Rationale: reduced volatility, scale growth rate, and contact resistance reported with Mn, Ti, La additions

# Screening Evaluation

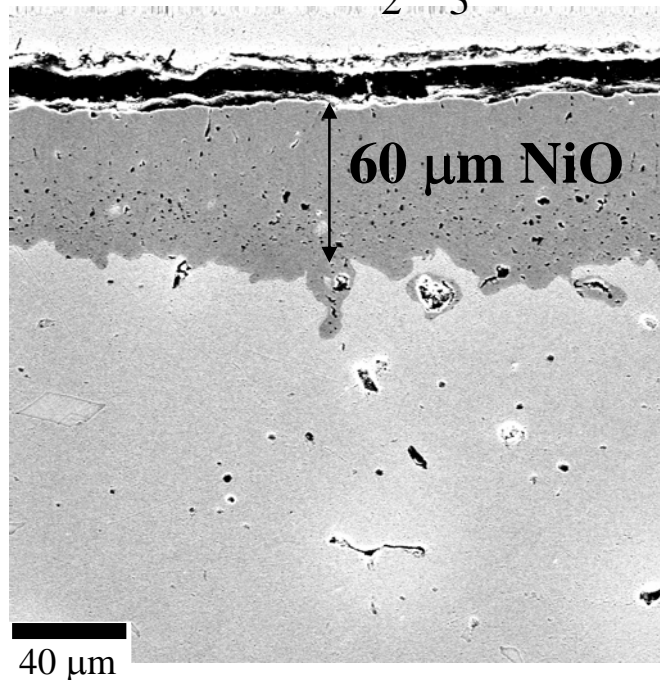
- Air oxidation screening: 3, 1 week cycles at 850°C (500 h Total)
- Area specific resistance (ASR) measurements
- In-cell stack test: 400-800 h at 850°C (isothermal)

# Adherent NiO Formed at 850°C in Air

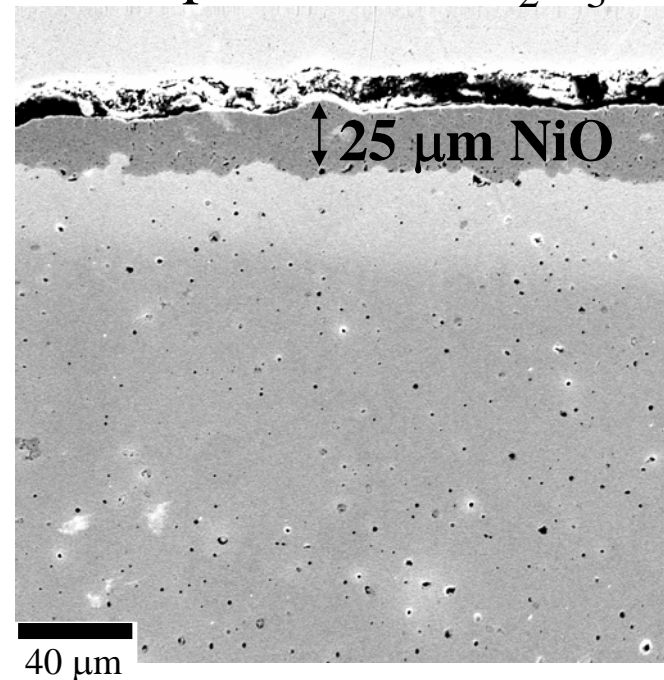
(similar behavior for 0.15Y and 0.3Y<sub>2</sub>O<sub>3</sub> doping)

SEM Cross-sections after 3, 1 week cycles (500 h), 850°C, Air

Ni-0.3Y<sub>2</sub>O<sub>3</sub>



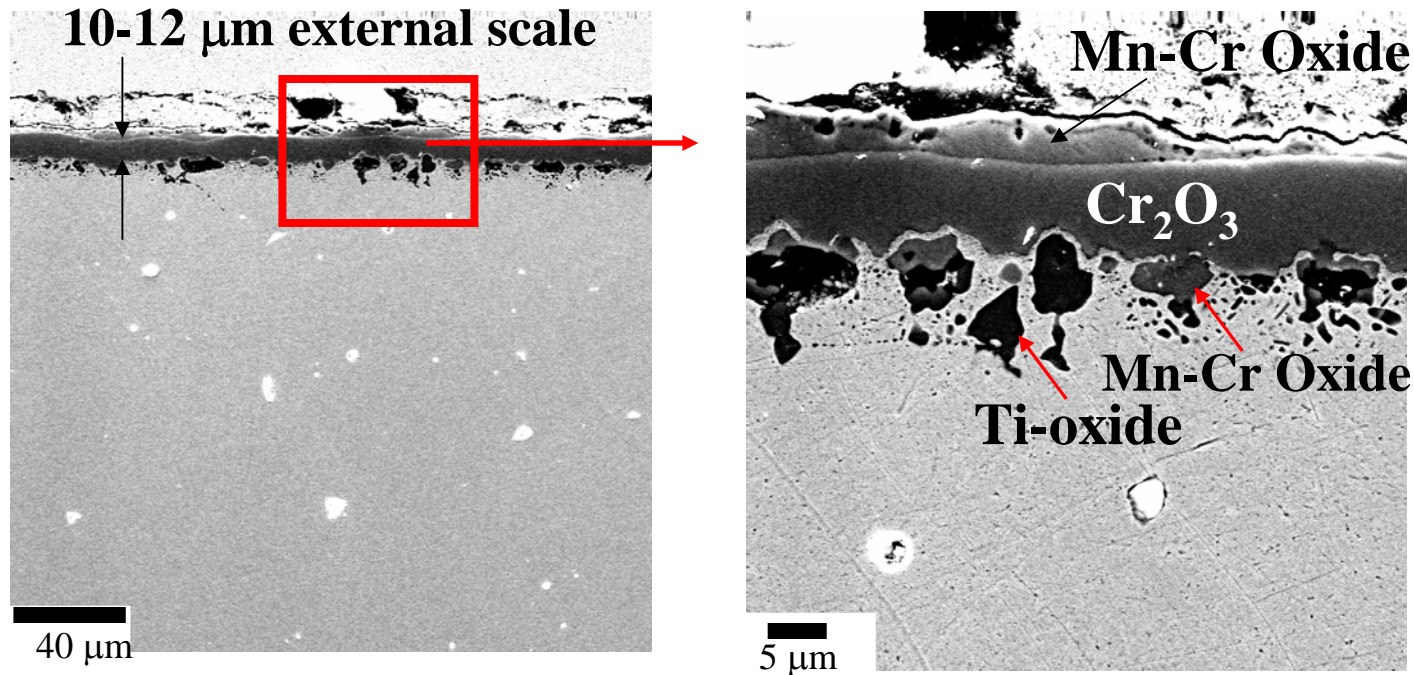
Li Doped, Ni-0.3Y<sub>2</sub>O<sub>3</sub>



- Li slowed NiO growth beyond that achieved with Y<sub>2</sub>O<sub>3</sub>
- NiO growth at 850°C in range of estimated growth rate for potentially acceptable resistivity (based on bulk NiO)

# Duplex Scale Formed on Fe-25Cr-1Mn-0.5Ti-0.4La at 850°C in Air

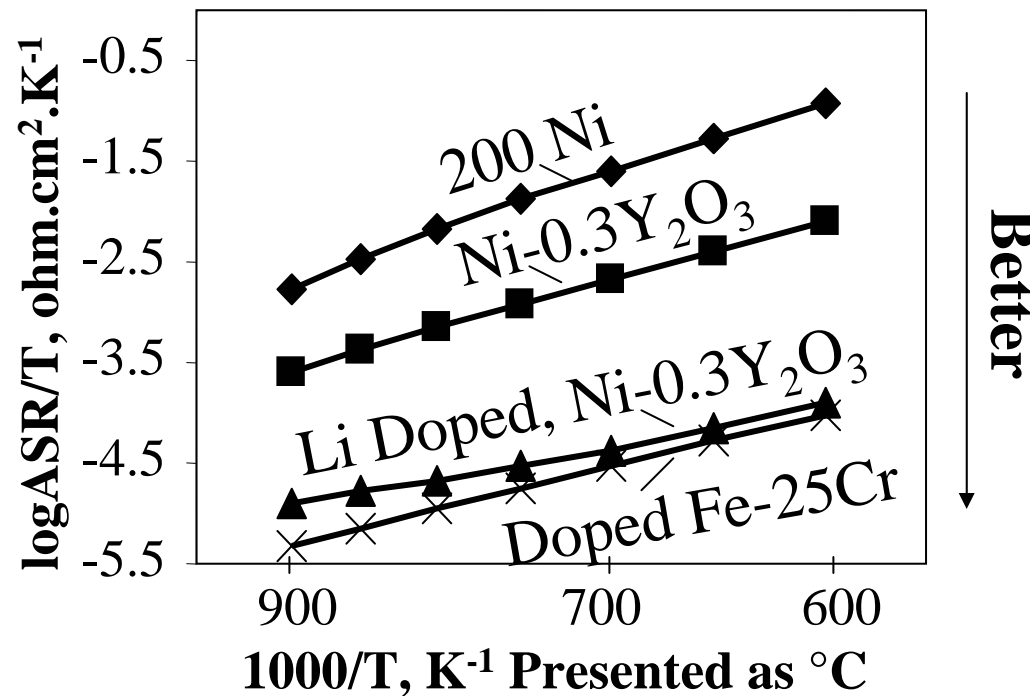
SEM Cross-section after 3, 1 week cycles (500 h), 850°C, Air



- Mn, Cr-based oxide (likely spinel) above continuous  $\text{Cr}_2\text{O}_3$
- Internal oxidation suggests overdoping of Ti, possibly La (levels not optimized)

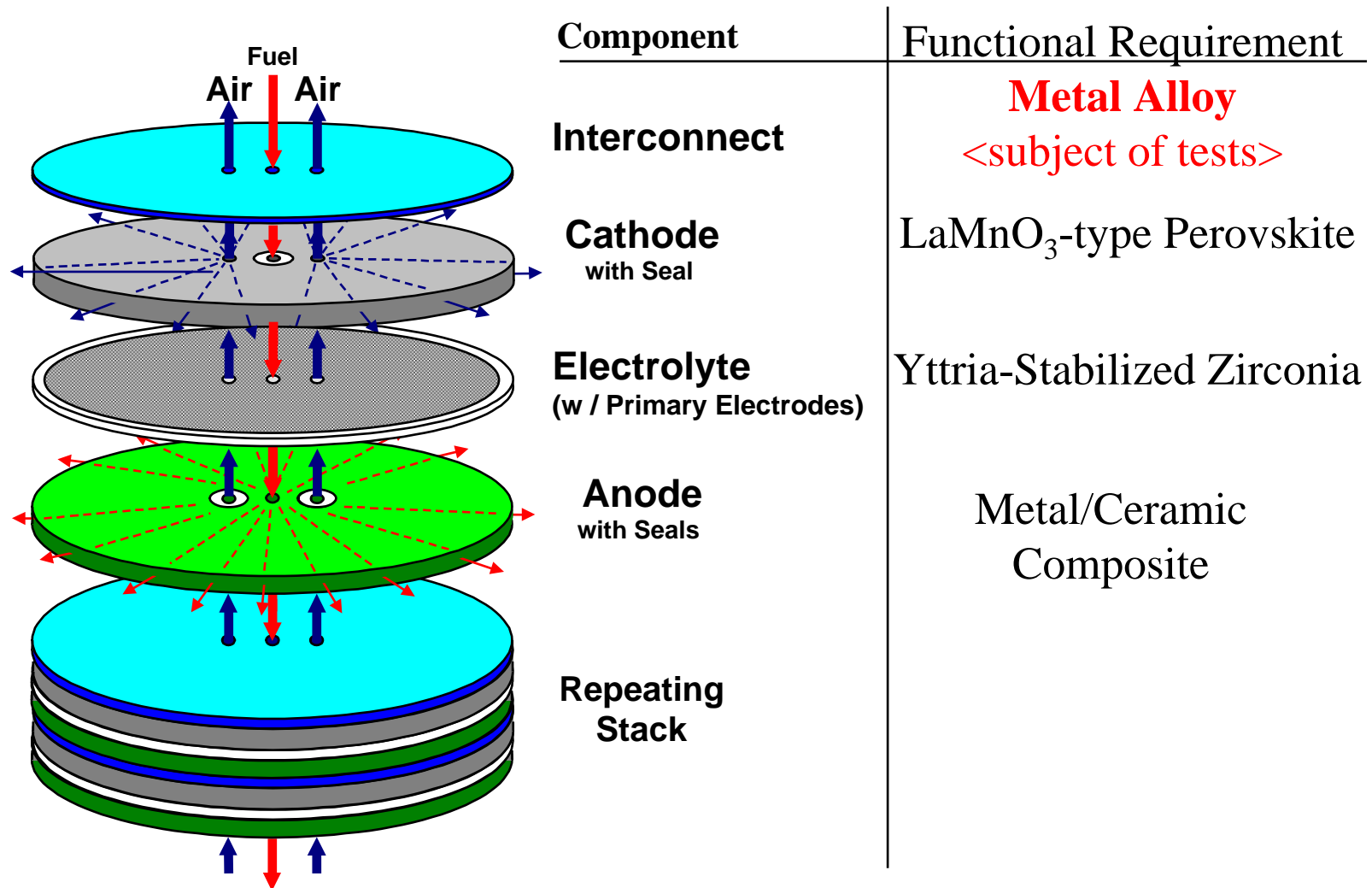
# Li-Doped Ni-0.3Y<sub>2</sub>O<sub>3</sub> Exhibits Similar ASR to Fe-25Cr-1Mn-0.5Ti-0.4La wt.%

Arrhenius Plot of Area Specific Resistance vs. 1/T  
3, 1 week cycles (500 h), 850°C, Air  
(Pt Electrode, DC 4 point method)



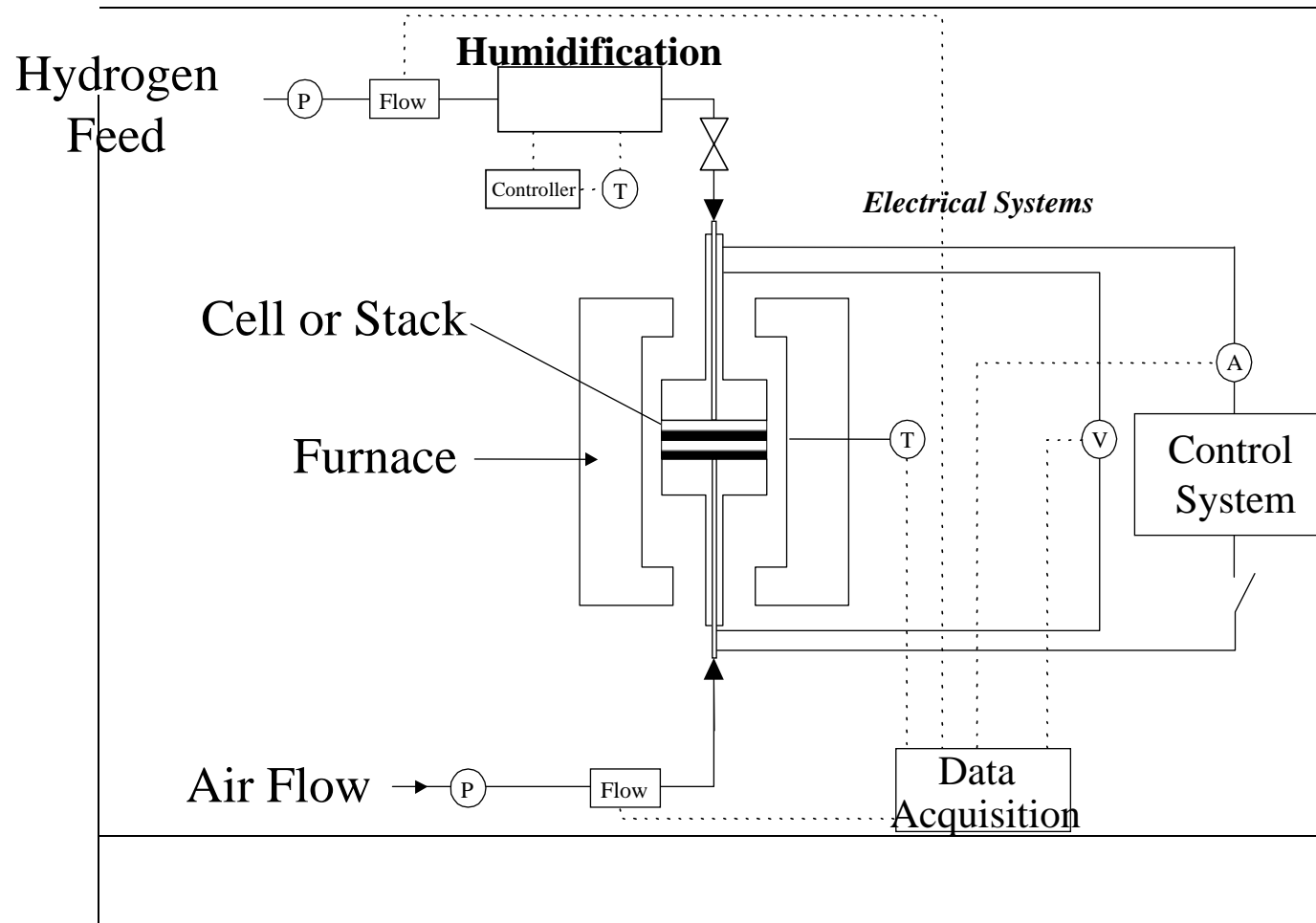
- Cross-section analysis of scale thickness not yet performed  
(ASR trends for Ni-alloys consistent w/oxidation mass change data)

# TMI's Radial Flow Cell



- Cell Design Tolerates Some Metal CTE Mismatch-Ideal Test Bed for Candidate Interconnect Alloys

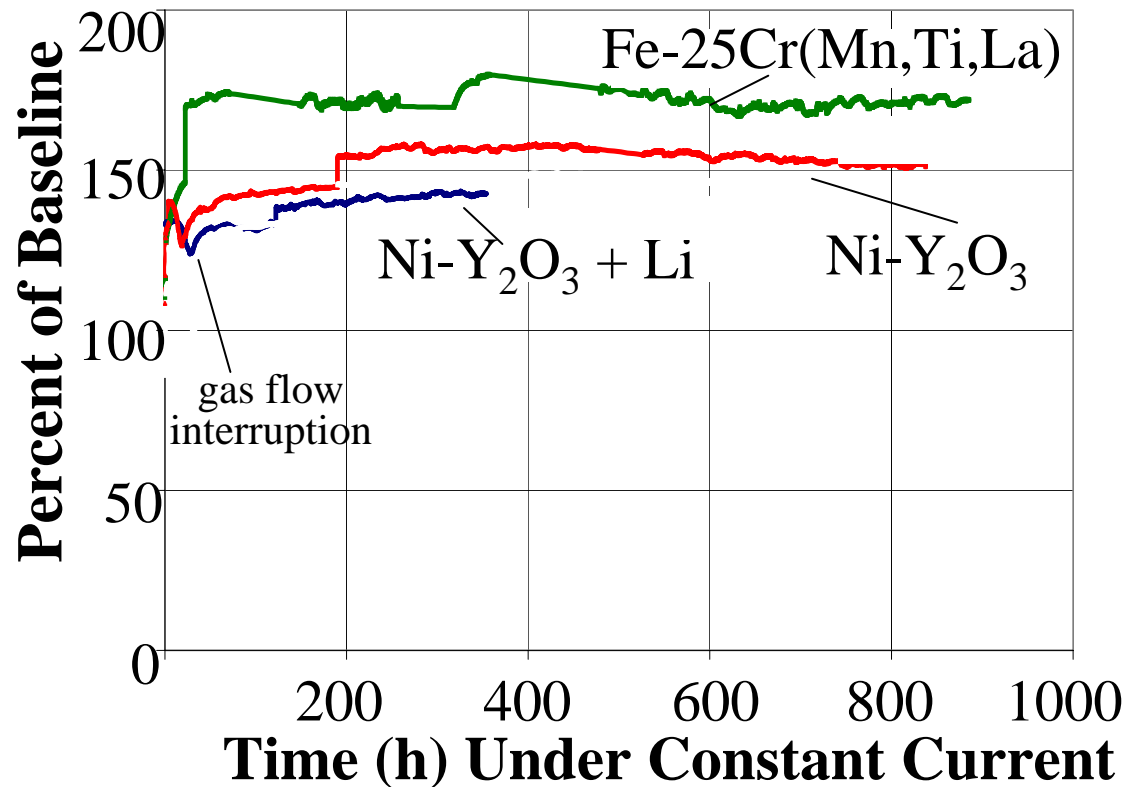
# Cell Test Configuration



- 2-5 Cell Stacks Tested at  $\sim 850^{\circ}\text{C}$  Run with Humidified  $\text{H}_2$

# Moderate Performance Improvement Over Conventional $\text{Cr}_2\text{O}_3$ -Forming Alloys

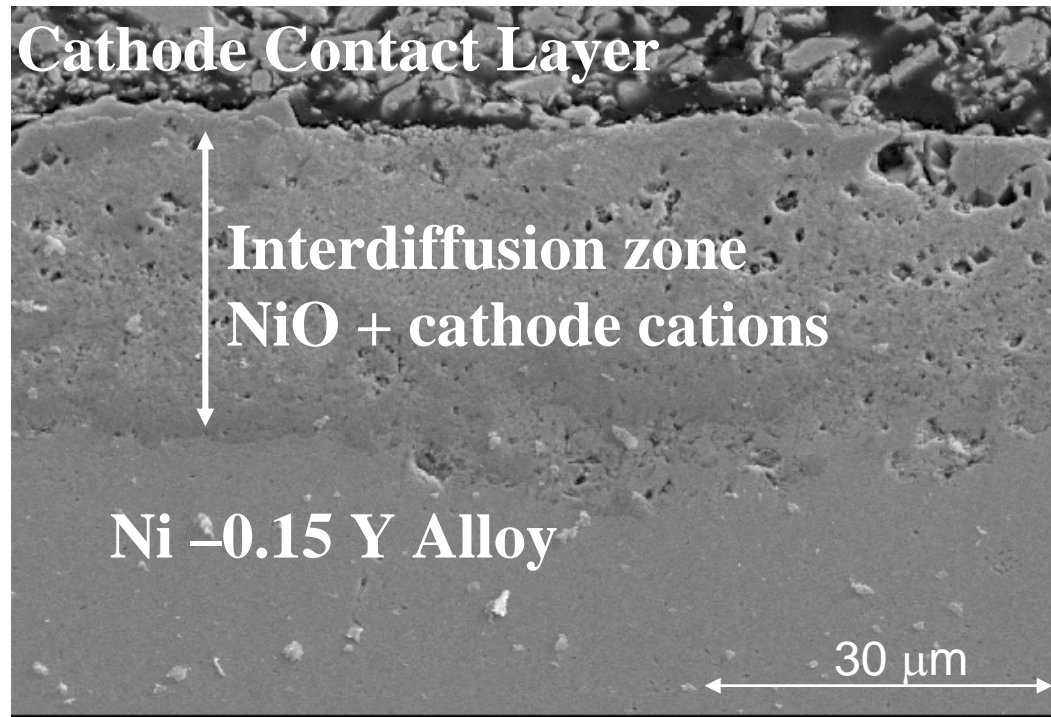
850°C In-Cell Performance Relative to 100% Baseline for Commercial  $\text{Cr}_2\text{O}_3$ -Forming Alloys



- Ferritic 1.7X better than baseline, Ni 1.6X baseline
- Li doping effect in Ni did not translate to better performance
- Stack degradation rates 2-3X greater than long term target rates

# Ni-0.15Y Alloy Reacted with Cathode (similar behavior for Ni-0.3Y<sub>2</sub>O<sub>3</sub>)

SEM Cross-Section of Ni Interconnect/Cathode Interface  
after ~ 600 h in-cell at 850°C



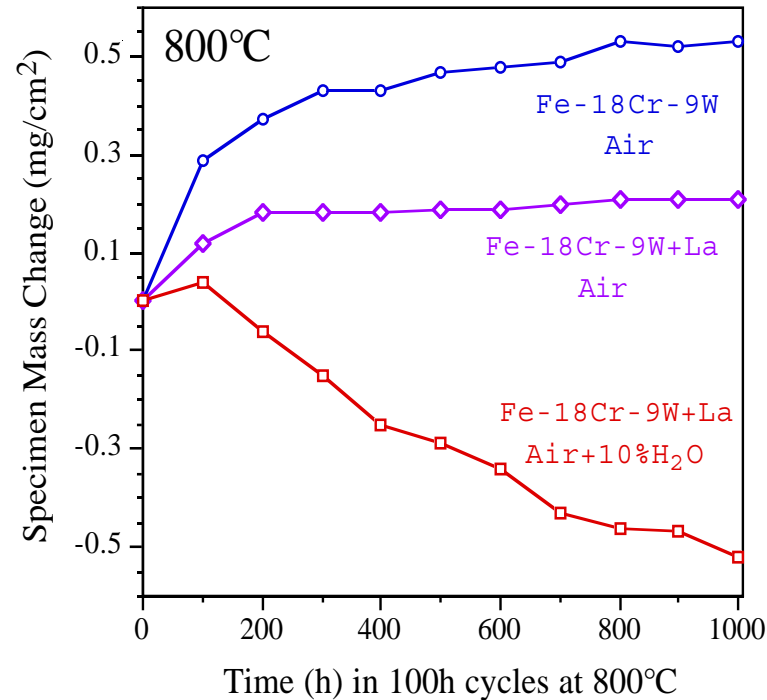
- No Ni alloy oxidation or reaction at anode contact layer
- Preliminary analysis of Fe25Cr(Mn,Ti,La) alloy revealed thin dense scale at anode and cathode-not yet analyzed

# **Alloy Optimization Will Require Detailed Oxidation and Electrical Resistivity Studies**

Ferritic Baseline Composition of Fe-18Cr-9W wt.%  
Selected for Study

- Ueda and Taimatsu, 2000 baseline composition for lower CTE (improved thermal compatibility with zirconia)
- Controlled levels of La, Mn, Ti (Quadakkers et al, 2000)
- Oxidation/Volatility Assessment in 10% H<sub>2</sub>O, 800-900°C, 1h or 100h cycles, 500-1000+ total h
- Post-Oxidation Area Specific Resistance (ASR) Measurements

## Performance of microalloyed Fe-18Cr-9W Laboratory oxidation testing at 800°C (1472°F)



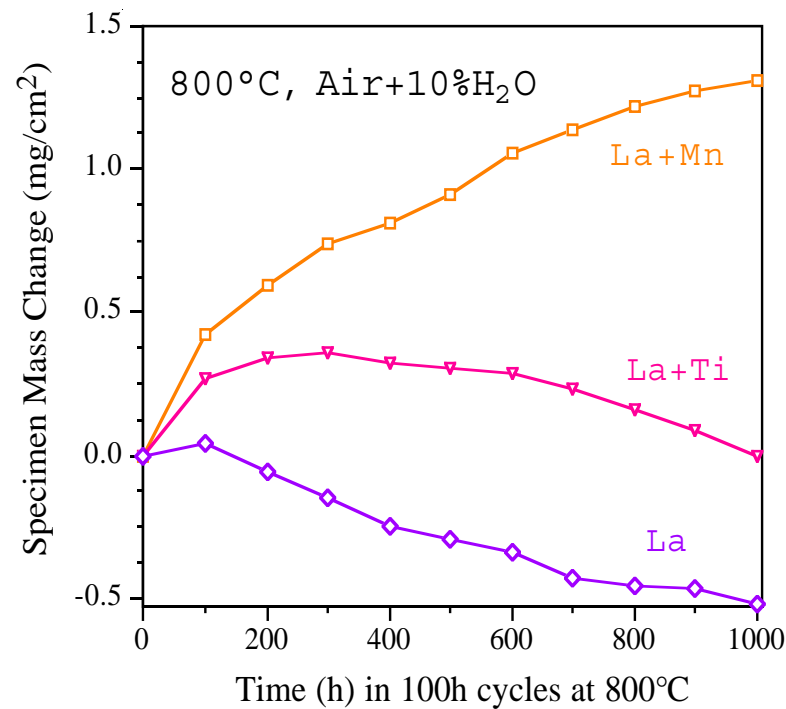
Base alloy - protective scale in air

La - reduces scale growth rate (lower mass gain)

Add H<sub>2</sub>O - mass loss due to volatilization of CrO<sub>2</sub>(OH)<sub>2</sub>

This volatilization causes a contamination problem in fuel cells!

## Performance of microalloyed Fe-18Cr-9W Laboratory oxidation testing at 800°C (1472°F)



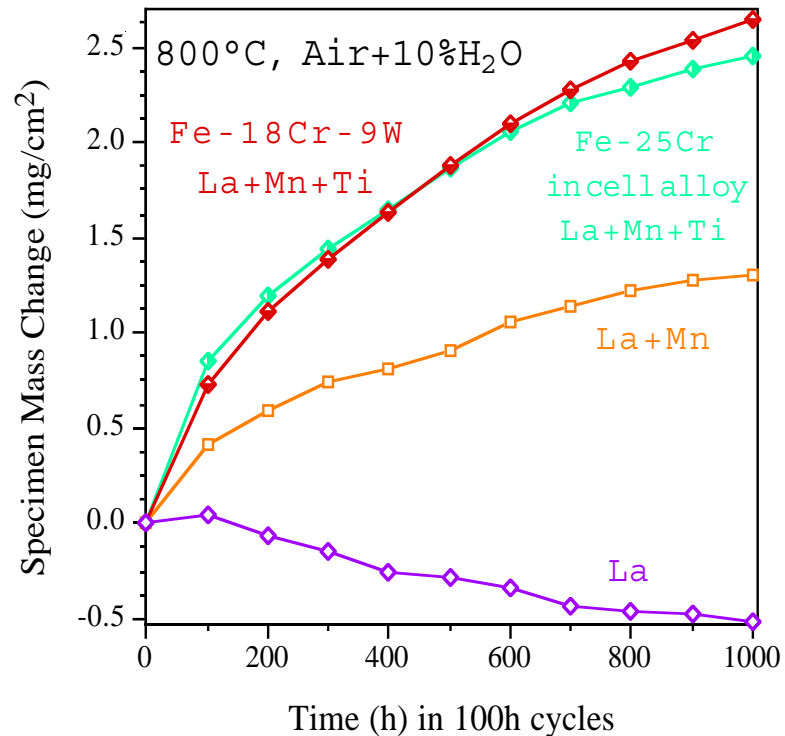
Try to minimize evaporation:

La+Ti - higher initial mass gain, but mass loss at later times

La+Mn - no mass loss detected, suggests reduction in volatility

# Optimization of microalloyed Fe-18Cr-9W

## Laboratory oxidation testing at 800°C (1472°F)

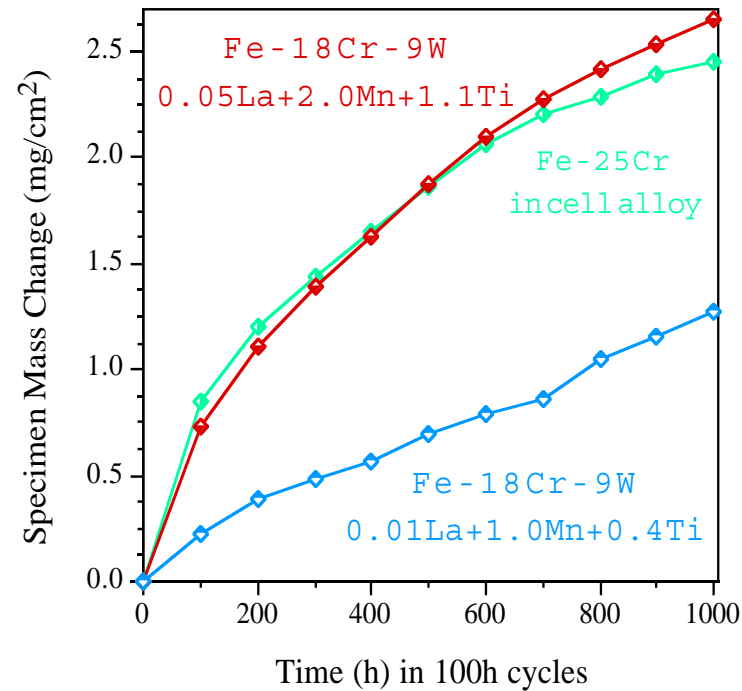


Combination of La+Mn+Ti reported to have best performance

Adding more elements to alloy leads to higher mass gains due to internal oxidation of La, Mn and Ti

# Optimization of microalloyed Fe-18Cr-9W

## Laboratory oxidation testing at 800°C (1472°F)



First attempt at optimization:

By dropping La, Mn and Ti (at.%):

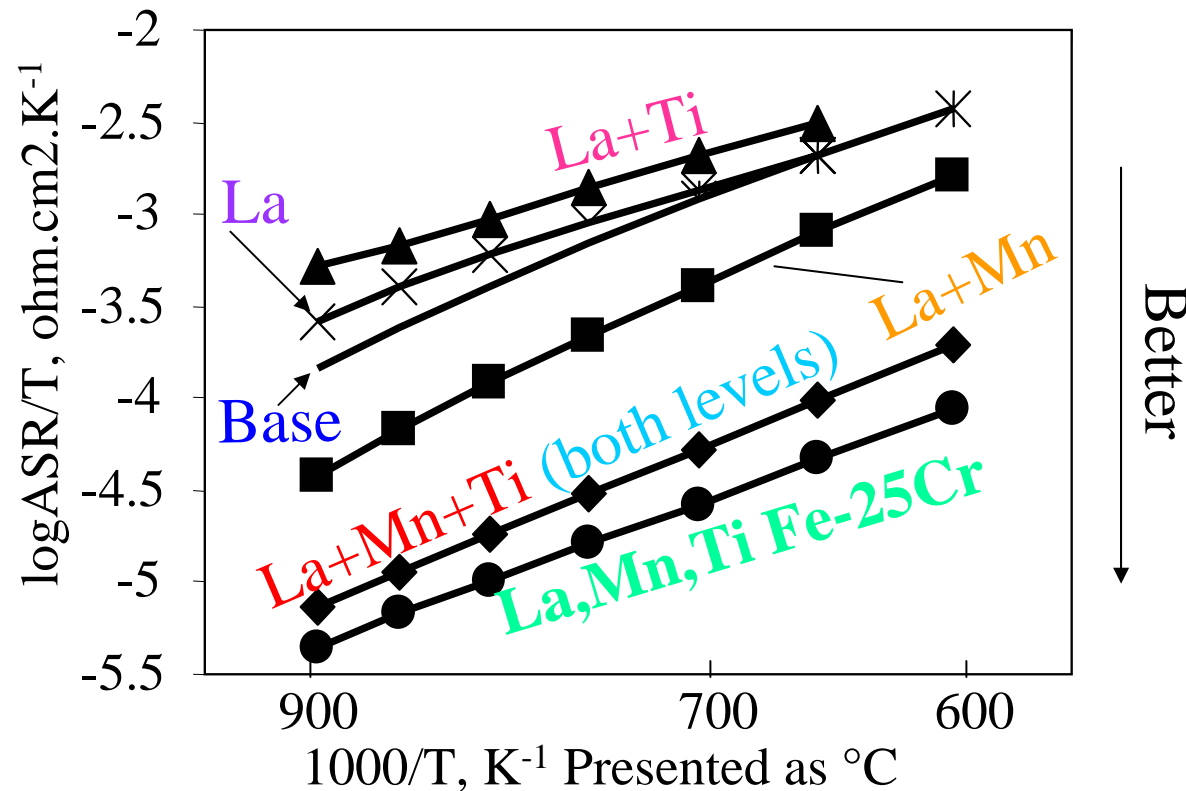
cut mass gain by 50% (in cell test: attack 2-3X high)

further optimization possible!

However, can't rely only on mass change data alone...

# Results Suggest Co-Doping of Mn and Ti Significantly Reduces Scale ASR

Arrhenius Plot of Area Specific Resistance vs.  $1/T$   
Fe-18Cr-9W Base, 550 1h Cycles, 10%  $H_2O$



- La,Mn,Ti synergistic trends consistent with Quadakkers et al.
- Need oxide thickness & chemistry to better assess results

# Summary

Using commercial  $\text{Cr}_2\text{O}_3$ -forming interconnects as baseline :

## •Microalloyed Ferritic $\text{Cr}_2\text{O}_3$ Former up to 80% Performance Improvement Over Baseline Alloy

- In-cell degradation rate too high (2-3X long term target)
- Series of Fe-Cr-W alloys indicated:
  - La: reduce  $\text{Cr}_2\text{O}_3$  growth rate
  - La +Mn: reduce  $\text{Cr}_2\text{O}_3$  evaporation (less cell contamination?)
  - La+Mn+Ti: synergistic decrease in ASR (Pt electrode)
- Further optimization of composition may be possible

## •Microalloyed Ni/NiO up to 60% Performance Improvement Over Baseline Alloy

- Comparable ASR to doped ferritic (Pt electrode)
- Reactivity with cathode may limit performance
- Degradation rate also too high (2-3X long term target)
- Merits further investigation (possibility as cladding)